EOS/ESD Association, Inc.



China ESD Forum Workshop October 14-15, 2020 **Anthea Hotel**

No. 108 Shui Ku Road, Xi Xiang Street, Shenzhen, Guangdong, China, 518101

This annual one-of-a-kind workshop/forum brings forth the realities of ESD requirements in light of the rapidly advancing semiconductor technologies requiring higher speeds of operations while balanced with much improved worldwide ESD factory control at fabs and assembly areas.

It is a two-day event to bring together electronics professionals to learn and exchange information about current issues of ESD requirements, and facilitate harmonization towards common goals for product cost savings.

Expert panel discussions provide intensive discussion and analysis that leads to valuable problem-solving exchanges.

and Lab Areas:

- ESD Control Measures in Electro-Static Protected Areas (EPAs)
- Measurements to Control CDM Events
- Defining Component-Level ESD Target Levels
- Absolute Maximum Ratings and Reliability Physics
- Learning from Physical Failure Analysis

System-Level ESD Design:

- System Efficient ESD Design (SEED): Co-Design of Semiconductor Components and Electronic Systems
- Disconnects between Component-Level and System-Level Protection
- Teardowns and Examples of System-Level Protection
- System Design Focusing on Soft and Hard Failure Prevention
- TVS Diode Characterization for Successful Application of the SEED Method

- HBM and CDM Testing and the Correct Implementation of the Test Standards
- Transmission Line Pulsing: Basics and Application Areas of TLP Testing
- System-Level ESD Testing: Basics, Best Practice Sharing and Avoiding Pitfalls

Chip-Level ESD Design:

- Radio-Frequency (RF), High-Voltage (HV), and Mixed-Signal ESD Protection Concepts
- Design Challenges for IC ESD Protection

Advanced Developments in ESD Design and **Testing:**

- ESD Stress by Charged Board Events (CBE)
- System ESD Stress and Its Impact on System Interfaces
- Development of Spice Simulation Models for ESD Simulation
- System-Level ESD Simulation: Live Demo
- Applying the SEED Method to Soft Failures





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- Sponsor can hold steering committee position and actively shape final content selections
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Examples from following applications areas that were discussed during previous workshop:

- Automotive ICs, Electronic Control Units (ECUs) and communication bus systems
- High-speed computer interfaces, such as USB 3.x, HDMI, Ethernet
- General purpose Input and Output circuits in nanometer IC technologies
- Over- and under-voltage-tolerant IC pins
- High-voltage and mixed-voltage-domain IC protection
- RF-Antenna and RF-Frontend protection

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Setting the Global Standards for Static Control!

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